

Form PTO-1449 INFORMATION DISCLOSURE CITATION <i>(Use several sheets if necessary)</i>		Attorney Docket No. 62020-1260	Serial No. 10/647,703
		Applicant Bakir, et al.	
		Filing Date 8/25/03	Group 2833

U.S. PATENT DOCUMENTS

Examiner Initials	Item	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
OR	A	4,380,365	4/19/83	Gross	350	96.18	5/23/79
	B	5,046,800	9/10/91	Blyler, Jr., et al.	385	131	10/9/90
	C	5,130,356	7/14/92	Feuerherd, et al.	524	96	2/1/90
	D	5,302,656	4/12/94	Kohara, et al.	524	579	4/10/91
	E	5,359,208	10/25/94	Katsuki, et al.	257	82	2/26/93
	F	5,454,196	7/18/95	Ohkawa, et al.	522	100	7/1/94
	G	5,462,995	10/31/95	Hosaka, et al.	525	332.1	6/9/92
	H	5,581,414	12/3/96	Snyder	359	819	2/22/93
	I	5,896,479	4/20/99	Vladic	385	59	4/9/97
	J	6,022,498	2/8/00	Buazza, et al.	264	1.38	4/19/96
OR	K	6,039,897	3/21/00	Lochhead, et al.	264	1.24	8/28/97

FOREIGN PATENT DOCUMENTS

		Document Number	Date	Country	Class	Subclass	Translation
							Yes No

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)

OR	L	Chen, et al.; Fully Embedded Board-Level Guided-Wave Optoelectronic Interconnects; June, 2000; Proceedings of IEEE, Vol. 88, No. 6; pp 780-793
OR	M	Wiesmann, et al.; Singlemode Polymer Waveguides for Optical Backplanes; December 5, 1996; Electronics Letters, Vol. 32, No. 25; pp 2329-2330
OR	N	Barry, et al.; Highly Efficient Coupling Between Single-Mode Fiber and Polymer Optical Waveguides; August, 1997; IEEE Transactions on Components, Packaging, and Manufacturing Technology - Part B, Vol. 20, No. 3; pp 225-228
OR	O	Lee, et al.; Fabrication of Polymeric Large-Core Waveguides for Optical Interconnects Using a Rubber Molding Process; January, 2000; IEEE Photonics Technology Letters, Vol. 12, No. 1; pp 62-64
OR	P	Schmeider, et al.; Electro-Optical Printed Circuit Board (EOPCB); 2000 Electronic Components and Technoogy Conference; pp 749-753
OR	Q	Mederer, et al.; 3Gb/s Data Transmission With GaAs VCSELs Over PCB Integrated Polymer Waveguides; September, 2001; IEEE Photonics Technology Letters, Vol. 13, No. 9; pp 1032-1034

* EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.

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DATE CONSIDERED:

7/18/05

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DR	R	6,156,394	12/5/00	Schultz Yamasaki, et al.	427	536	4/17/98
	S	6,206,673	3/27/01	Lipscomb, et al.	425	174.4	5/30/95
	T	6,253,004	6/26/01	Lee, et al.	385	31	7/9/99
	U	6,259,567	7/10/01	Brown, et.al.	359	668	11/23/98
	V	6,262,414	7/17/01	Mitsuhashi	250	216	7/27/99
	W	6,272,275	8/7/01	Cortright, et al.	385	129	6/25/99
	X	6,281,508	8/28/01	Lee, et al.	250	396	2/8/99
	Y	6,432,328	8/13/02	Hamanaka, et al.	264	1.36	1/10/01
DR	Z	6,500,603	12/31/02	Shioda	430	321	11/9/00
	AA						
	BB						

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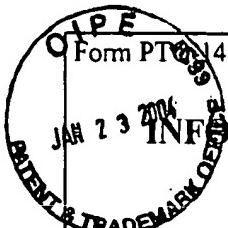
		Document Number	Date	Country	Class	Subclass	Translation
							Yes No

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)

DR	CC	Schröder, et al.; Polymer Optical Interconnects for PCB; 2001; Session 13: Photonic Polymers II; pp 337-343
DR	DD	Glukh, et al.; High performance Polymeric Materials for Waveguide Applications; August, 2000; SPIE - The International Society for Optical Engineering, near, Nonlinear, and Power Limiting Organics, San Diego, Volume 4106; pp 1-11
DR	EE	Liu, et al.; Plastic VCSEL Array Packaging and High Density Polymer Waveguides for Board and Backplane Optical Interconnect; 1998; Electronic Components and Technology Conference; pp 999-1005
DR	FF	Bakir, et al.; Sea of Dual Mode Polymer Pillar I/O Interconnections for Gigascale Integration; 2003; IEEE International Solid State Circuits Conference; 8 pages
DR	GG	Beuret, et al.; Microfabrication of 3D Multidirectional Inclined Structure by UV lithography and Electroplating; Micro Electro Mechanical Systems, 1994, MEMS'94, Proceedings, IEEE Workshop on January 25-28, 1994; pp 81-85
DR	HH	Wang, et al.; Studies on A Novel Flip-Chip Interconnect Structure-Pillar Bump; Electronic Components and Technology Conference, 2001, Proceedings, 51st, 29 May-1, June 2001; pp 945-949

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Form PTO-449

INFORMATION DISCLOSURE CITATION

(Use several sheets if necessary)

Attorney Docket No.
62020-1260Serial No.
10/647,703Applicant
Bakir, et al.Filing Date
8/25/03Group
2833**U.S. PATENT DOCUMENTS**

Examiner Initials	Item	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
	II						
	JJ						
	KK						

FOREIGN PATENT DOCUMENTS

		Document Number	Date	Country	Class	Subclass	Translation
							Yes No

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)

<i>DR</i>	LL	Bakir, et al.; Sea of Polymer Pillars: Dual-Mode Electrical Optical Input/Output Interconnections; in Proc. of Int. Interconnect Technology Conference; pp. 77-79; 2003
<i>DR</i>	MM	Bakir, et al.; Sea of Polymer Pillars: Compliant Wafer-Level Electrical-Optical Chip I/O Interconnections; IEEE Photonics Technology Letters, Vol. 15, No. 11, November 2003; pp 1567-1569
<i>DR</i>	NN	Bakir, et al.; Optical Transmission of Polymer Pillars for Chip I/O Optical Interconnections; IEEE Photonics Technology Letters, Vol. 16, No. 1, January 2004; pp 117-119
<i>DR</i>	OO	Chandrasekhar, et al.; Modeling and Characterization of the Polymer Stud Grid Array (PSGA) Package: Electrical, Thermal and Thermo-Mechanical Qualification; IEEE Transactions on Electronics Packaging Manufacturing, Vol. 26, No. 1, January 2003; pp 54-67

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EXAMINER'S SIGNATURE: *DR Roja*

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